ASSOCIATION CONNECTING ASSOCIATION CONNECTING LECTRONICS INDUSTRIES	IPC. Bannockt	ourn. Illinois. A	Il rights reserved un ntions.	nder both	This docume level parts, t	ent is a declaratio he declaration en	n of the substand compasses all lo	es within the manufactur wer level materials for w	rer listed ite hich the m	em. Note: if anufacturer	the item is an as has engineering	sembly with low responsibility.	
	21.1 IPC Web Site for Information on IPC-1752 Standard For http://www.ipc.org/IPC-175x Dis				 Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information 					on			
upplier Information													
Company name* Compar			mpany unique ID			Unique ID Authority				Response Date*			
onsemi										2024-05-09			
Contact Name Title - Contact			ıct			Phone - Contact*			Email - Contact*				
Product-Env-Stewards Product Envi			nviro Compliance		NA			Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Repres			resentative		Phone - Representative*			Email - Representative*					
Product-Env-Stewards Product Env			Enviro Compliance		NA			Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Veight*	UOM	Unit Type	
	FSB5055	SB50550BSL SPM5 V3 INV 50		0V 2.40hm		2024-05-09		СРА		355.2	mg	Each	
Anufacturing Proccess Informa	ation					·		·					
Terminal Plating / Grid Array M	Terminal Plating / Grid Array Material Terminal Base A		Alloy J	-STD-020 MSL	. Rating	Peak Proces	s Body Temper	ature Max Time at Peak	Temperatu	ire Numbe	er of Reflow Cyc	cles	
Matte Tin (Sn) - annealed CU Alloy		3	3		260	C	30	second	ls 3				
omments													
FTENTION: MSL 3 Rated item requir	es Bake and D	ry Pack (after	electrical test)										
or more information regarding materia	l composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
lease indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, admium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part ontains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall necompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, s of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. 'ompany acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not idependently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the ertification in the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the 'arranty' rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	24.0	mg	Supplier	Silicon (Si)	7440-21-3		24	mg
Die Attach	6.0	mg	Supplier	Silver (Ag)	7440-22-4		4.56	mg
			Supplier	Phenolic Resin-2	54208-63-8		1.44	mg
Die Attach Solder	4.8	mg	Supplier	Silver (Ag)	7440-22-4		0.12	mg
			А	Lead (Pb)	7439-92-1	7a	4.44	mg
			Supplier	Tin (Sn)	7440-31-5		0.24	mg
Lead Frame	1370.0	mg	Supplier	Silver (Ag)	7440-22-4		20.002	mg
			В	Nickel (Ni)	7440-02-0		30.003	mg
			Supplier	Iron (Fe)	7439-89-6		1.37	mg
			Supplier	Copper (Cu)	7440-50-8		1318.214	mg
			Supplier	Phosphorus (P)	7723-14-0		0.411	mg
Mold Compound-Black	1890.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		132.3	mg
			Supplier	Carbon Black (C)	1333-86-4		18.9	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		661.5	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		132.3	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		945	mg
Plating	56.4	mg	Supplier	Tin (Sn)	7440-31-5		56.4	mg
Wire Bond - Cu	4.0	mg	Supplier	Palladium (Pd)	7440-05-3		0.08	mg
			Supplier	Copper (Cu)	7440-50-8		3.92	mg